

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S) Fu, C. et al.

GROUP ART UNIT: 3723

APPLN. NO.: 09/712,749

EXAMINER: NGUYEN, David T.

FILED: 11/14/2000

RESPONSE UNDER 37 CFR 1.116

EXPEDITED PROCEDURE

TITLE:

LOW PROFILE INTEGRATED MODULE INTERCONNECTS AND
METHOD OF FABRICATION

Certificate of Transmission under 37 CFR 1.8

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RESPONSE UNDER 37 CFR 1.116

Honorable Assistant Commissioner of Patents,
Washington, D.C. 20231

SIR:

In response to the Office Action mailed JANUARY 17, 2003, please amend
and reconsider the above-identified application as shown below in the included
pages entitled "Amended Claims" and "Remarks."